

ABSTRACT

An adhesive tape constructed of a base material 11 and an adhesive layer 12 is used as a substrate 1. Droplets 2 formed of a liquid containing electrically conductive ultra-fine particles dispersed therein are disposed in a specified wiring pattern on the adhesive layer 12. The adhesive tape 1 is put into a hot-air oven 3 to dry the disperse medium from the droplets 2. Accordingly, a wiring layer 21 made of silver particles contained in the droplets 2 is formed on the adhesive layer 12 of the adhesive tape 1.